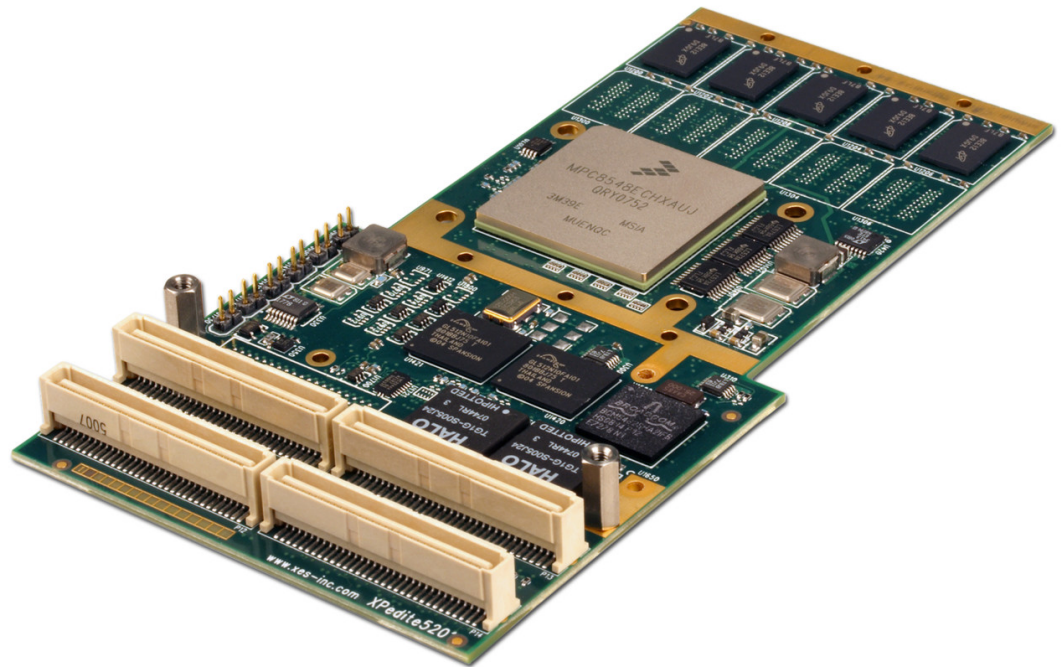


XPedite5201

End of Life

NXP PowerQUICC™ III MPC8548E Processor-Based Conduction-Cooled XMC/PMC Module **Please contact X-ES Sales**

- ▶ NXP (formerly Freescale) PowerQUICC™ III MPC8548E processor at up to 1.333 GHz
- ▶ Conduction-cooled XMC/PMC module
- ▶ 133 MHz, 64-bit PCI-X
- ▶ x8 PCI Express
- ▶ Up to 4 GB DDR2-533 SDRAM
- ▶ 512 kB L2 cache
- ▶ Double-precision Floating-Point Unit (FPU)
- ▶ Up to 256 MB of soldered NOR flash
- ▶ Up to 4 GB of NAND flash
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP
- ▶ Green Hills INTEGRITY BSP
- ▶ Linux BSP



XPedite5201

The XPedite5201 is a high-performance, conduction-cooled Processor PCI Mezzanine Card (PrPMC)/XMC featuring the NXP (formerly Freescale) PowerQUICC™ III MPC8548E processor running at up to 1.333 GHz. The onboard PowerQUICC™ III provides integrated 64-bit PCI-X, DDR2-400/533 SDRAM, PCI Express, and two Gigabit Ethernet interfaces, making the XPedite5201 an optimal solution for communications processing and general computing applications alike.

When used as an XMC (VITA 42) module, the x8 PCI Express interface can be used, in parallel or in substitution of the PCI-X interface. With software supplied by Extreme Engineering Solutions, the XPedite5201 can be installed on standard VME and CompactPCI (cPCI) platforms as well as custom motherboards that support PMC sites.

The XPedite5201 provides two Gigabit Ethernet interfaces via the P14 backplane connector.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

9901 Silicon Prairie Parkway • Verona, WI 53593
 Phone: 608.833.1155 • Fax: 608.827.6171
 sales@xes-inc.com • <https://www.xes-inc.com>

Processor

- NXP (formerly Freescale) PowerQUICC™ III MPC8548E processor
- Embedded PowerPC e500 core at 1.0 to 1.333 GHz
- 3065 MIPS at 1.333 GHz
- 32 kB L1 instruction/data caches
- 512 kB L2 cache
- Double-precision Floating-Point Unit (FPU)
- Integrated MMU
- DDR2-533 SDRAM interface
- x8 PCI Express
- 133 MHz, 64-bit PCI-X 1.0a interface
- Four 10/100/1000 Mbps, IEEE 802.3-compliant Ethernet controllers
- Two serial controllers
- Two I²C controllers

Memory

- Up to 4 GB DDR2-533 SDRAM
- Up to 256 MB NOR flash
- Up to 4 GB NAND flash
- 2 kB SEEPROM

XMC

- x8 PCI Express (VITA 42.3)
- IPMI FRU support
- GPIO on user data

RTC

- M41T00 I²C timekeeper
- 60 hour clock retention

Rear I/O

- Two Gigabit Ethernet ports
- Four GPIO pins
- Two RS-232 serial ports

Software

- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Linux BSP

Physical Characteristics

- XMC/PMC conduction-cooled form factor
- Dimensions: 149 mm x 74 mm, 10 mm stacking height

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Maximum power consumption: 13.35 W (with 1.333 GHz processor), 10.5 W (with 1 GHz processor)

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

